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MS AF  
REPLY UNDER  
37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2814

PATENT  
0763-0173P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Dong K. SOHN et al. Conf.: 9674  
Appl. No.: 10/620,608 Group: 2814  
Filed: July 17, 2003 Examiner: Long Pham  
For: METHOD OF FORMING FILM FOR REDUCED  
OHMIC CONTACT RESISTANCE AND TERNARY  
PHASE LAYER AMORPHOUS DIFFUSION BARRIER

REPLY AFTER FINAL UNDER 37 C.F.R. § 1.116

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

October 28, 2004

Sir:

In reply to the outstanding Office Action dated August 2, 2004, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

This reply includes: amendments to the specification, claims and remarks.

Please  
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LP/11/5/04